PRELIMINARY **CY7C1399**

32K x 8 3.3V Static RAM

Features

- **Single 3.3V power supply**
- **Ideal for low-voltage cache memory applications**
- **High speed**
  - **12 ns**
- **Low active power**
  - **255 mW**
- **Low standby power**
  - **90 mW**
- **2.0V data retention**
  - **100 µW**
- **Easy memory expansion with $\overline{CE}$ and $\overline{OE}$ features**
- **Plastic DIP, SOJ, and TSOP packaging**

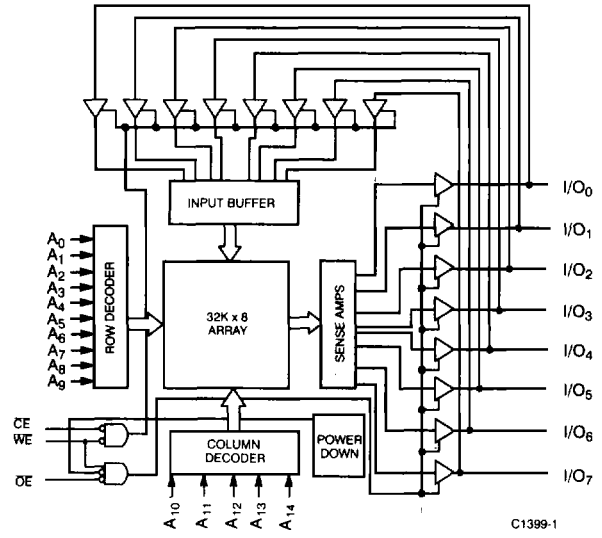
Functional Description

The CY7C1399 is a high-performance 3.3V CMOS static RAM organized as 32,768 words by 8 bits. Easy memory expansion is provided by an active LOW chip enable ($\overline{CE}$) and active LOW output enable ($\overline{OE}$) and three-state drivers. The device has an automatic power-down feature, reducing the power consumption by more than 60% when deselected.

An active LOW write enable signal ($\overline{WE}$) controls the writing/reading operation of the memory. When $\overline{CE}$ and $\overline{WE}$ inputs are both LOW, data on the eight data input/output pins (I/O_0 through I/O_7) is written into the memory location addressed by the address present on the address pins (A_0 through A_{14}). Reading the device is accomplished by selecting the device and enabling the outputs, $\overline{CE}$ and $\overline{OE}$ active LOW, while $\overline{WE}$ remains inactive or HIGH. Under these conditions, the contents of the location addressed by the information on address pins is present on the eight data input/output pins.

The input/output pins remain in a high-impedance state unless the chip is selected, outputs are enabled, and write enable ($\overline{WE}$) is HIGH. The CY7C1399 is available in standard 300-mil-wide DIP and SOJ packages. A die coat is used to ensure alpha immunity.

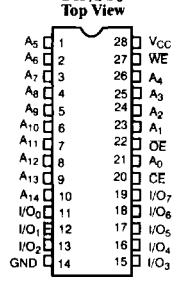
Logic Block Diagram



C1399-1

Pin Configurations

DIP/SOJ
Top View



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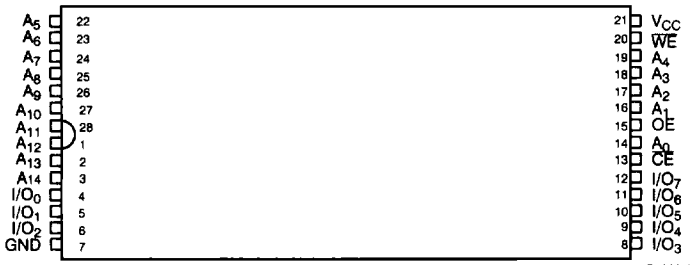
Selection Guide

	7C1399–12	7C1399–15	7C1399–20	7C1399–25	7C1399–35
Maximum Access Time (ns)	12	15	20	25	35
Maximum Operating Current (mA)	60	55	50	45	40
Maximum Standby Current (mA)	5	5	5	5	5

Shaded area contains advanced information.

Pin Configurations (continued)

TSOP
Top View



C1399-3

Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature ..... −65°C to +150°C

Ambient Temperature with Power Applied ..... −55°C to +125°C

Supply Voltage on V_{CC} to Relative GND[1] .. −0.5V to +4.6V

DC Voltage Applied to Outputs in High Z State[1] ..... −0.5V to V_{CC} + 0.5V

DC Input Voltage[1] ..... −0.5V to V_{CC} + 0.5V

Output Current into Outputs (LOW) ..... 20 mA

Static Discharge Voltage ..... >2001V (per MIL-STD-883, Method 3015)

Latch-Up Current ..... >200 mA

Operating Range

Range	Ambient Temperature	V_{CC}
Commercial	0°C to +70°C	3.3V ±0.3 mV

Electrical Characteristics Over the Operating Range[2]

Parameter	Description	Test Conditions	7C1399-12		7C1399-15		7C1399-20		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	
V_{OH}	Output HIGH Voltage	V_{CC} = Min., I_{OH} = −4.0 mA	2.4		2.4		2.4		V
V_{OL}	Output LOW Voltage	V_{CC} = Min., I_{OL} = −8.0 mA		0.4		0.4		0.4	V
V_{IH}	Input HIGH Voltage		2.0	V_{CC} +0.3V	2.0	V_{CC} +0.3V	2.0	V_{CC} +0.3V	V
V_{IL}	Input LOW Voltage[2]		−0.3	0.8	−0.3	0.8	−0.3	0.8	V
I_{IX}	Input Load Current		−1	+1	−1	+1	−1	+1	µA
I_{OZ}	Output Leakage Current	GND ≤ V_I ≤ V_{CC}, Output Disabled	−5	+5	−5	+5	−5	+5	µA
I_{OS}	Output Short Circuit Current[3]	V_{CC} = Max., V_{OUT} = GND		−300		−300		−300	mA
I_{CC}	V_{CC} Operating Supply Current	V_{CC} = Max., I_{OUT} = 0 mA, f = f_{MAX} = $1/t_{RC}$		60		55		50	mA
I_{SB1}	Automatic CE Power-Down Current — TTL Inputs	Max. V_{CC}, $\overline{CE}_1 \geq V_{IH}$, or $CE_2 \leq V_{IL}$, $V_{IN} \geq V_{IH}$, or $V_{IN} \leq V_{IL}$, f = f_{MAX}		5		5		5	mA
I_{SB2}	Automatic CE Power-Down Current — TTL Inputs	Max. V_{CC}, $\overline{CE}_1 \geq V_{CC}$, 0.3V or $CE_2 \leq 0.3V$, $V_{IN} \geq V_{CC}$ − 0.3V, or $V_{IN} \leq 0.3V$, f=0		50		50		50	µA

Shaded area contains advanced information.

Notes:

1. Minimum voltage is equal to − 2.0V for pulse durations of less than 20 ns.
2. See the last page of this specification for Group A subgroup testing information.
3. Not more than one output should be shorted at one time. Duration of the short circuit should not exceed 30 seconds.

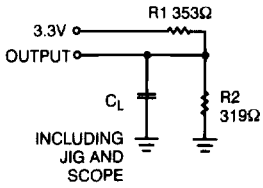
Electrical Characteristics Over the Operating Range[2] (continued)

Parameter	Description	Test Conditions	7C1399–25		7C1399–35		Unit
			Min.	Max.	Min.	Max.	
V_{OH}	Output HIGH Voltage	V_{CC} = Min., I_{OH} = −2.0 mA	2.4		2.4		V
V_{OL}	Output LOW Voltage	V_{CC} = Min., I_{OL} = 2.0 mA		0.4		0.4	V
V_{IH}	Input HIGH Voltage		2.0	V_{CC} +0.3V	2.0	V_{CC} +0.3V	V
V_{IL}	Input LOW Voltage[2]		−0.3	0.8	−0.3	0.8	V
I_{IX}	Input Load Current		−1	+1	−1	+1	µA
I_{OZ}	Output Leakage Current	GND ≤ V_I ≤ V_{CC}, Output Disabled	−5	+5	−5	+5	µA
I_{OS}	Output Short Circuit Current[3]	V_{CC} = Max., V_{OUT} = GND		−300		−300	mA
I_{CC}	V_{CC} Operating Supply Current	V_{CC} = Max., I_{OUT} = 0 mA, f = f_{MAX} = $1/t_{RC}$		45		40	mA
I_{SB1}	Automatic CE Power-Down Current — TTL Inputs	Max. V_{CC}, $\overline{CE}_1 \geq V_{IH}$ or $CE_2 \leq V_{IL}$, $V_{IN} \geq V_{IH}$ or $V_{IN} \leq V_{IL}$, f = f_{MAX}		5		5	mA
I_{SB2}	Automatic CE Power-Down Current — TTL Inputs	Max. V_{CC}, $\overline{CE}_1 \geq V_{CC}$ 0.3V or $CE_2 \leq 0.3V$, $V_{IN} \geq V_{CC}$ − 0.3V or $V_{IN} \leq 0.3V$, f=0		50		50	µA

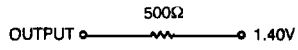
Capacitance[4]

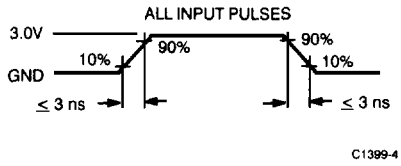
Parameter	Description	Test Conditions	Max.	Unit
C_{IN}: Addresses	Input Capacitance	T_A = 25°C, f = 1 MHz, V_{CC} = 3.3V	5	pF
C_{IN}: Controls			6	pF
C_{OUT}	Output Capacitance		6	pF

AC Test Loads and Waveforms



Equivalent to: THÉVENIN EQUIVALENT





Note:
4. Tested initially and after any design or process changes that may affect these parameters.

Switching Characteristics Over the Operating Range[2, 5]

Parameter	Description	7C1399–12		7C1399–15		7C1399–20		7C1399–25		7C1399–35		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
READ CYCLE												
t_{RC}	Read Cycle Time	12		15		20		25		35		ns
t_{AA}	Address to Data Valid		12		15		20		25		35	ns
t_{OHA}	Data Hold from Address Change	3		3		3		3		3		ns
t_{ACE}	$\overline{CE}$ LOW to Data Valid		12		15		20		25		35	ns
t_{DOE}	$\overline{OE}$ LOW to Data Valid		5		6		7		8		10	ns
t_{LZOE}	$\overline{OE}$ LOW to Low Z[7]	0		0		0		0		0		ns
t_{HZOE}	$\overline{OE}$ HIGH to High Z[6, 7]		5		6		6		7		7	ns
t_{LZCE}	$\overline{CE}$ LOW to Low Z[7]	3		3		3		3		3		ns
t_{HZCE}	$\overline{CE}$ HIGH to High Z[6, 7]		6		7		7		8		8	ns
t_{PU}	$\overline{CE}$ LOW to Power-Up	0		0		0		0		0		ns
t_{PD}	$\overline{CE}$ HIGH to Power-Down		12		15		20		25		35	ns
WRITE CYCLE[8, 9]												
t_{WC}	Write Cycle Time	12		15		20		25		35		ns
t_{SCE}	$\overline{CE}$ LOW to Write End	8		10		12		15		20		ns
t_{AW}	Address Set-Up to Write End	8		10		12		15		20		ns
t_{HA}	Address Hold from Write End	0		0		0		0		0		ns
t_{SA}	Address Set-Up to Write Start	0		0		0		0		0		ns
t_{PWE}	$\overline{WE}$ Pulse Width	8		10		12		15		20		ns
t_{SD}	Data Set-Up to Write End	6		9		10		11		12		ns
t_{HD}	Data Hold from Write End	0		0		0		0		0		ns
t_{HZWE}	$\overline{WE}$ LOW to High Z[6]		7		7		7		7		7	ns
t_{LZWE}	$\overline{WE}$ HIGH to Low Z[7]	3		3		3		3		3		ns

Shaded area contains advanced information.

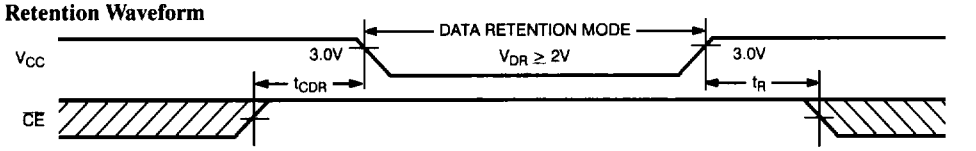
Data Retention Characteristics (Over the Operating Range)

Parameter	Description	Conditions[10]	Min.	Max.	Unit
V_{DR}	V_{CC} for Data Retention		2.0		V
I_{CCDR}	Data Retention Current	$V_{CC} = V_{DR} = 2.0V$, $\overline{CE} \geq V_{CC} - 0.3V$, $V_{IN} \geq V_{CC} - 0.3V$ or $V_{IN} \leq 0.3V$		20	µA
t_{CDR}[4]	Chip Deselect to Data Retention Time		0		ns
t_R[4]	Operation Recovery Time		t_{RC}		ns

Notes:

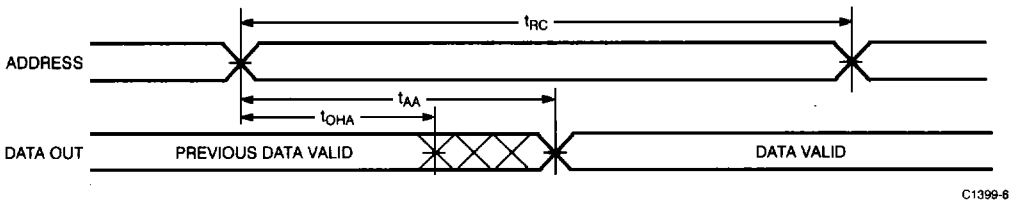
5. Test conditions assume signal transition time of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified I_{OL}/I_{OH} and capacitance C_L = 30 pF.
6. t_{HZOE}, t_{HZCE}, and t_{HZWE} are specified with C_L = 5 pF as in AC Test Loads. Transition is measured ±500 mV from steady state voltage.
7. At any given temperature and voltage condition, t_{HZCE} is less than t_{LZCE}, t_{HZOE} is less than t_{LZOE}, and t_{HZWE} is less than t_{LZWE} for any given device.
8. The internal write time of the memory is defined by the overlap of $\overline{CE}$ LOW and $\overline{WE}$ LOW. Both signals must be LOW to initiate a write and either signal can terminate a write by going HIGH. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the write.
9. The minimum write cycle time for write cycle #3 ($\overline{WE}$ controlled, $\overline{OE}$ LOW) is the sum of t_{HZWE} and t_{SD}.
10. No input may exceed V_{CC} + 0.3V.

Data Retention Waveform

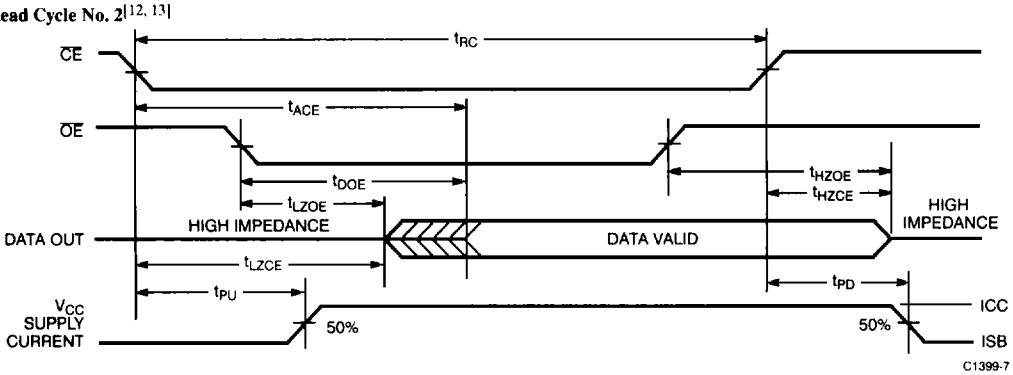


Switching Waveforms

Read Cycle No. 1[11, 12]



Read Cycle No. 2[12, 13]

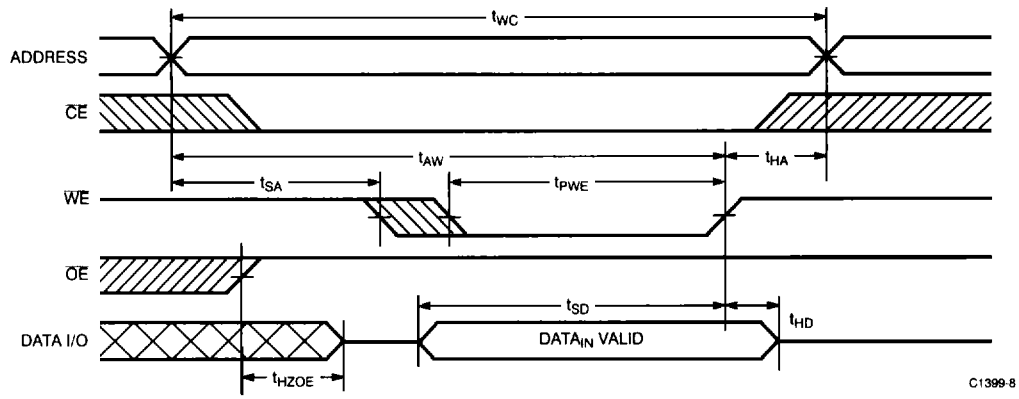


Notes:

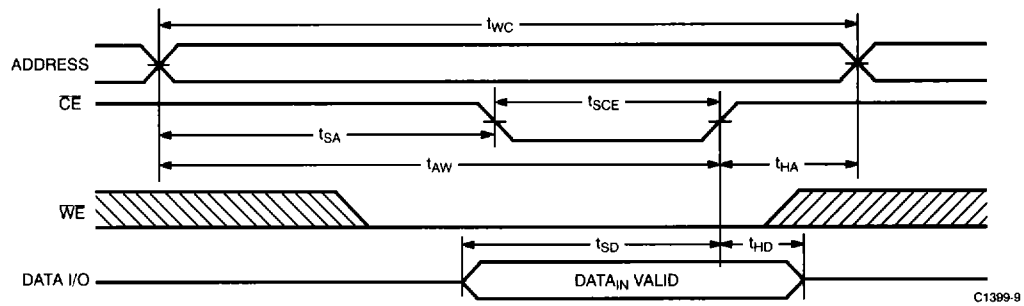
11. Device is continuously selected. $\overline{OE}$, $\overline{CE}$ = V_{IL}.
12. $\overline{WE}$ is HIGH for read cycle.
13. Address valid prior to or coincident with $\overline{CE}$ transition LOW.

Switching Waveforms (continued)

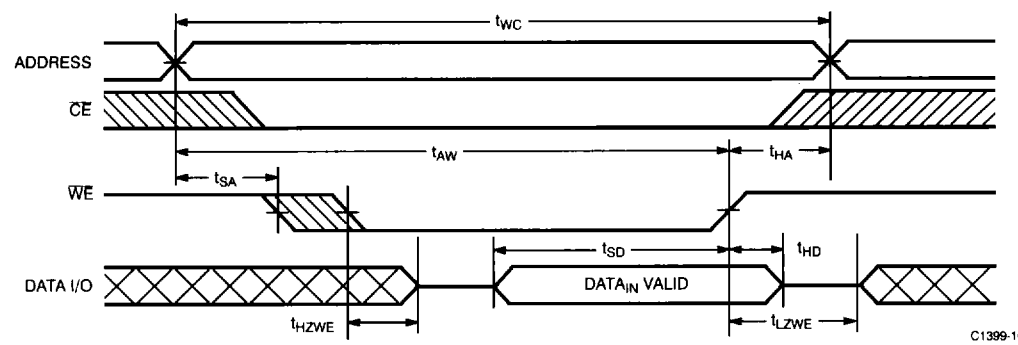
Write Cycle No. 1 ($\overline{WE}$ Controlled)[8, 14, 15]



Write Cycle No. 2 ($\overline{CE}$ Controlled)[8, 14, 15]



Write Cycle No. 3 ($\overline{WE}$ Controlled, $\overline{OE}$ LOW)[9, 15]



Notes:

14. Data I/O is high impedance if $\overline{OE}$ = V_{IH}.
15. If $\overline{CE}$ goes HIGH simultaneously with $\overline{WE}$ HIGH, the output remains in a high-impedance state.

Truth Table

$\overline{CE}$	$\overline{WE}$	$\overline{OE}$	Input/Output	Mode	Power
H	X	X	High Z	Deselect/Power-Down	Standby (I_{SB})
L	H	L	Data Out	Read	Active (I_{CC})
L	L	X	Data In	Write	Active (I_{CC})
L	H	H	High Z	Deselect, Output Disabled	Active (I_{CC})

Ordering Information

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
12	CY7C1399-12PC	P21	28-Lead (300-Mil) Molded DIP	Commercial
	CY7C1399-12VC	V21	28-Lead Molded SOJ	
	CY7C1399-12ZC	Z28	28-Lead Thin Small Outline Package	
15	CY7C1399-15PC	P21	28-Lead (300-Mil) Molded DIP	Commercial
	CY7C1399-15VC	V21	28-Lead Molded SOJ	
	CY7C1399-15ZC	Z28	28-Lead Thin Small Outline Package	
20	CY7C1399-20PC	P21	28-Lead (300-Mil) Molded DIP	Commercial
	CY7C1399-20VC	V21	28-Lead Molded SOJ	
	CY7C1399-20ZC	Z28	28-Lead Thin Small Outline Package	
25	CY7C1399-25PC	P21	28-Lead (300-Mil) Molded DIP	Commercial
	CY7C1399-25VC	V21	28-Lead Molded SOJ	
	CY7C1399-25ZC	Z28	28-Lead Thin Small Outline Package	
35	CY7C1399-35PC	P21	28-Lead (300-Mil) Molded DIP	Commercial
	CY7C1399-35VC	V21	28-Lead Molded SOJ	
	CY7C1399-35ZC	Z28	28-Lead Thin Small Outline Package	

Shaded area contains advanced information.

MILITARY SPECIFICATIONS
Group A Subgroup Testing

DC Characteristics

Parameter	Subgroups
V_{OH}	1, 2, 3
V_{OL}	1, 2, 3
V_{IH}	1, 2, 3
V_{IL} Max.	1, 2, 3
I_{IX}	1, 2, 3
I_{OZ}	1, 2, 3
I_{CC}	1, 2, 3
I_{SB1}	1, 2, 3
I_{SB2}	1, 2, 3

Switching Characteristics

Parameter	Subgroups
READ CYCLE	
t_{RC}	7, 8, 9, 10, 11
t_{AA}	7, 8, 9, 10, 11
t_{OHA}	7, 8, 9, 10, 11
t_{ACE}	7, 8, 9, 10, 11
t_{DOE}	7, 8, 9, 10, 11
WRITE CYCLE	
t_{WC}	7, 8, 9, 10, 11
t_{SCE}	7, 8, 9, 10, 11
t_{AW}	7, 8, 9, 10, 11
t_{HA}	7, 8, 9, 10, 11
t_{SA}	7, 8, 9, 10, 11
t_{PWE}	7, 8, 9, 10, 11
t_{SD}	7, 8, 9, 10, 11
t_{HD}	7, 8, 9, 10, 11

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